

## **AMENDMENT TO CLAIMS**

**[Deleted material is struck-through and added material is underlined]**

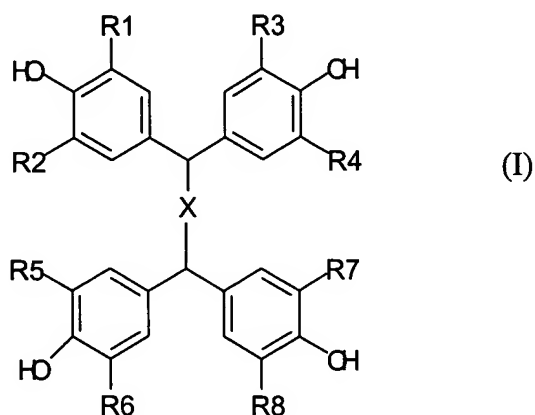
1. - 5. (Cancelled)

6. (Currently Amended) An epoxy resin composition comprising:

an epoxy resin prior to curing,

a non-clathrated curing agent reacting with an epoxy group of the epoxy resin to cure the resin, and

a tetrakisphenol compound represented by a general formula (I) as a curing accelerator catalyst,



wherein X represents  $(CH_2)_n$ , wherein n is 0, 1, 2 or 3, and  $R^1$  to  $R^8$  each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or  $C_1$ - $C_6$  alkyl, a halogen or a  $C_1$ - $C_6$  alkoxy,

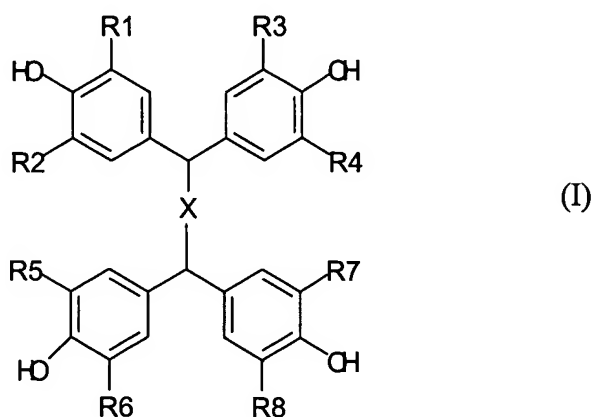
**wherein mono-substituted dicyandiamides is not used as an additive component,**

**and**

**wherein the content of said tetrakisphenol compound represented in formula (I) is a range from 0.001 to 0.1 mole based on 1 mole of the epoxy group.**

7. (Canceled)

8. (Currently Amended) A method for curing an epoxy resin comprising a step of mixing a non-clathrated curing agent reacting with an epoxy group of the epoxy resin to cure the resin and a tetrakisphenol compound represented by a general formula (I) as a curing accelerator catalyst with a non-curing epoxy resin,



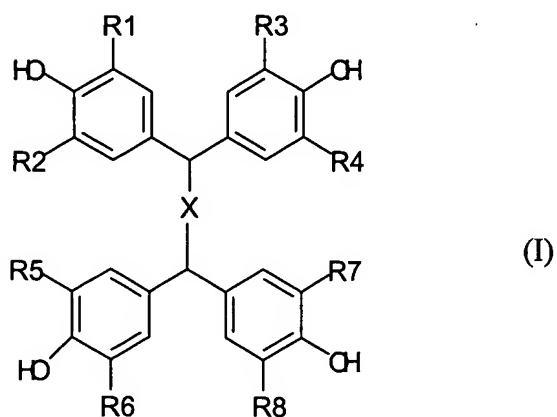
wherein X represents  $(CH_2)_n$ , wherein n is 0, 1, 2 or 3, and  $R^1$  to  $R^8$  each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or  $C_1$ - $C_6$  alkyl, a halogen or a  $C_1$ - $C_6$  alkoxy,

**wherein mono-substituted dicyandiamides is not used as an additive component,**  
**and**

**wherein the content of said tetrakisphenol compound represented in formula (I) is a range from 0.001 to 0.1 mole based on 1 mole of the epoxy group..**

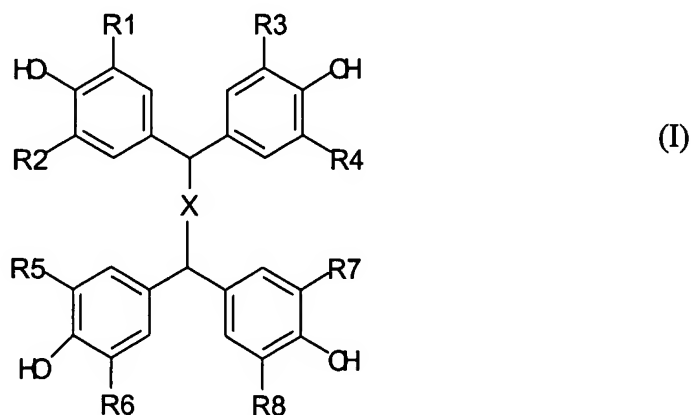
9. (Canceled)

10. (Withdrawn) A curative for epoxy resin, comprising a clathrate comprising:  
a tetrakisphenol compound represented by a general formula (I) and a compound  
reacting with an epoxy group to cure an epoxy resin,



wherein X represents  $(CH_2)_n$ , wherein n is 0, 1, 2 or 3, and  $R^1$  to  $R^8$  each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or  $C_1$ - $C_6$  alkyl, a halogen or a  $C_1$ - $C_6$  alkoxy.

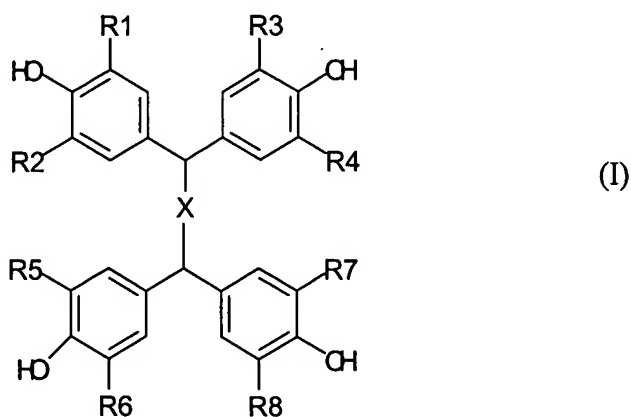
11. (Withdrawn) A curing accelerator for epoxy resin, comprising a clathrate  
comprising a tetrakisphenol compound represented by a general formula (I) and a compound  
accelerating the curing of a compound reacting with an epoxy group to cure an epoxy resin,



wherein X represents  $(CH_2)_n$ , wherein n is 0, 1, 2 or 3, and  $R^1$  to  $R^8$  each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or  $C_1$ - $C_6$  alkyl, a halogen or a  $C_1$ - $C_6$  alkoxy.

12. (Withdrawn) An epoxy resin composition comprising a non-curing epoxy resin, and a clathrate comprising a tetrakisphenol compound represented by a general formula (I) and a compound reacting with an epoxy group of the epoxy resin to cure the resin; and

a clathrate comprising a tetrakisphenol compound represented by a general formula (I) and a compound accelerating the curing of a compound reacting with an epoxy group to cure an epoxy resin,



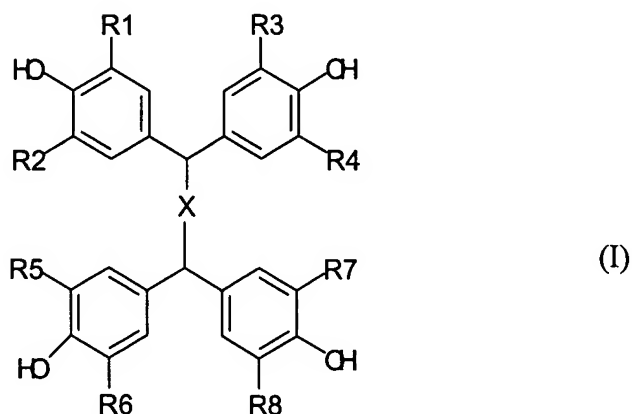
wherein X represents  $(CH_2)_n$ , wherein n is 0, 1, 2 or 3, and  $R^1$  to  $R^8$  each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or  $C_1$ - $C_6$  alkyl, a halogen or a  $C_1$ - $C_6$  alkoxy.

13. (Withdrawn) The epoxy resin composition according to claim 11, wherein the content of a tetrakisphenol compound represented by a general formula (I) in the clathrate is in a range of from 0.001 to 0.1 mole based on 1 mole of the epoxy group.

14. (Withdrawn) The epoxy resin composition according to claim 12, wherein the content of a tetrakisphenol compound represented by a general formula (I) in the clathrate is in a range of from 0.001 to 0.1 mole based on 1 mole of the epoxy group.

15. (Withdrawn) A method for curing an epoxy resin composition comprising the steps of:

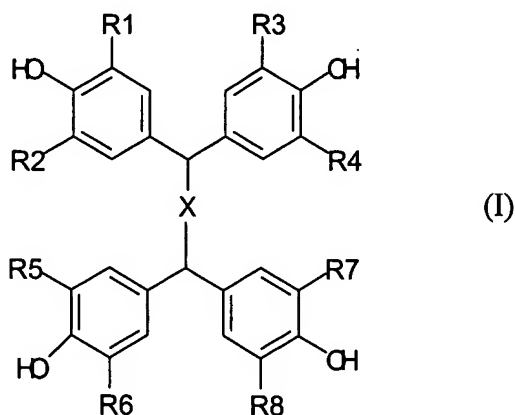
a clathrate comprising a tetrakisphenol compound represented by a general formula (I) and a compound reacting with an epoxy group of the epoxy resin to cure the resin is added and mixed to a non-curing epoxy resin, and then the mixture is heated to a predetermined temperature,



wherein X represents  $(CH_2)_n$ , wherein n is 0, 1, 2 or 3, and  $R^1$  to  $R^8$  each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or  $C_1$ - $C_6$  alkyl, a halogen or a  $C_1$ - $C_6$  alkoxy.

16. (Withdrawn) A method for curing an epoxy resin composition comprising the steps of:

a clathrate comprising a tetrakisphenol compound represented by a general formula (I) and a compound reacting with an epoxy group of the epoxy resin to cure the resin, and a clathrate comprising a tetrakisphenol compound represented by a general formula (I) and a compound accelerating the curing of a compound reacting with an epoxy group to cure an epoxy resin are added and mixed to a non-curing epoxy resin, and then the mixture is heated to a predetermined temperature,



wherein X represents  $(CH_2)_n$ , wherein n is 0, 1, 2 or 3, and  $R^1$  to  $R^8$  each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or  $C_1$ - $C_6$  alkyl, a halogen or a  $C_1$ - $C_6$  alkoxy.

17. (Withdrawn) The method for curing an epoxy resin composition according to claim 15, wherein the content of the tetrakisphenol compound represented by a general formula (I) in the clathrate is in a range of from 0.001 to 0.1 mole based on 1 mole of the epoxy group.

18. (Withdrawn) The method for curing an epoxy resin composition according to claim 16, wherein the content of the tetrakisphenol compound represented by a general formula (I) in the clathrate is in a range of from 0.001 to 0.1 mole based on 1 mole of the epoxy group.